



# Thin Film Approach

to the miniturization of Microwave & RF Filters

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Microwave Products Group



## Introduction to MPG



Mission-CriticalComponents & Subsystems





4 Business Units

 Expertise in communication-based products for demanding applications





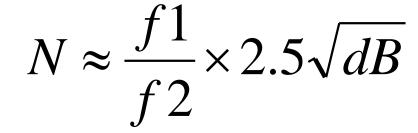


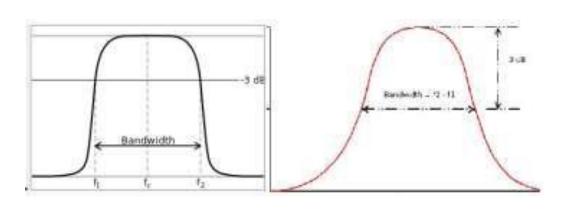


# Filter Design & Mathematical Methods



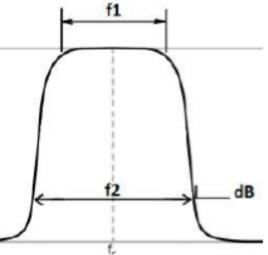
Approximate 
$$Q = 8.7x Fc \ x (N-1.5) / bw \ x insertion loss$$





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$$Q = 8.7x Fc \ x (N-1.5) / bw \ x insertion loss$$







# Traditional Equipment

- Lumped Equipment
- Dielectric Resonator
- Helical Filters
- Cavity Filters











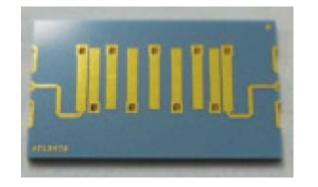
## Thin Film

## **Typical Characteristics**

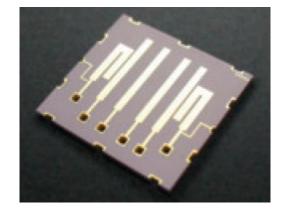
- RF Power handling up to 20 watts
- Steep Selectivity "n" 2 to 16 poles
- Fractional bandwidths up to 80%
- Solder or chip and wire surface mount design

## **Typical Filter types**

- Bandpass 700MHz to 26GHz
- Lowpass 700MHz to 26GHz
- Highpass 700MHz to 40GHz
- Duplexers 1GHz to 30GHz





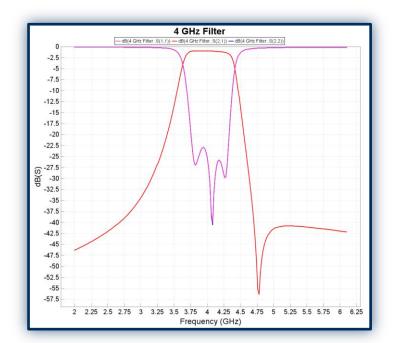








## Thin Film



Above: 4 GHz Bandpass filter response. Size: 9 x 9 mm.

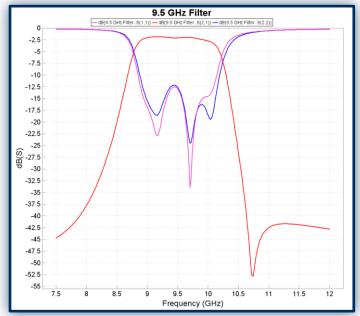


7.5 GHz Filter — dB(7.5 GHz Filter..S(1,1)) — dB(7.5 GHz Filter..S(2,1)) — dB(7.5 GHz Filter..S(2,2) -2.5 -7.5 -12.5 -15 -17.5 -20 -22.5 -25 (S) -27.5 GB -30 -32.5 -35 -37.5 -40 -42.5 -47.5 -50 -52.5 -55 -57.5 6.5 6.75 7.25 8.25 8.5 8.75 Frequency (GHz)

**Above:** 7.5 GHz Bandpass filter response. Size: 9 x 7 mm.







**Above:** 9.5 GHz Bandpass filter response. Size: 9 x 7 mm.







## Thin Film Filter – Notes



#### **Insertion Loss**

Insertion loss is a combination of multiple sources of loss, which include: Dielectric Loss (related to Df or Loss Tangent), Connector Losses, Impedance Mismatches (Reflections), Conductor Losses and Radiation Losses.

From a design perspective, the primary sources for insertion loss to consider in terms of ceramic performance are the dielectric loss and the conductive losses.

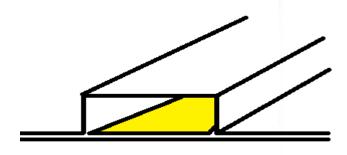
At frequencies up to 3GHz with very low loss materials (loss tangent 0.0003), conductive loss might dominate dielectric loss 3 to 1. As frequencies increase, the conductive loss and dielectric loss ratio will change to a point where they could be similar in value depending on the material performance across frequencies.



## Thin Film Filter – Notes



## **Fixing filter to ground**



Solder attachment process is difficult to repeat accurately as frequency increases. Board may "float" on solder.

Surface mount transitions become difficult to align and stray capacitance has a significant impact on circuit performance. Parasitics become difficult to model.

Epoxy bond technique may give better registration. Thermal bond also good. Place a 2 to 3 mil layer of epoxy (Araldite HY5052 [ablebond] or similar). Positive pressure on circuit may be required to give good adhesion.

If extremes of temperature are to be handled consider the thermal expansion of different materials Aluminium 21 ppm, CG = 9 ppm, CF = 9ppm.





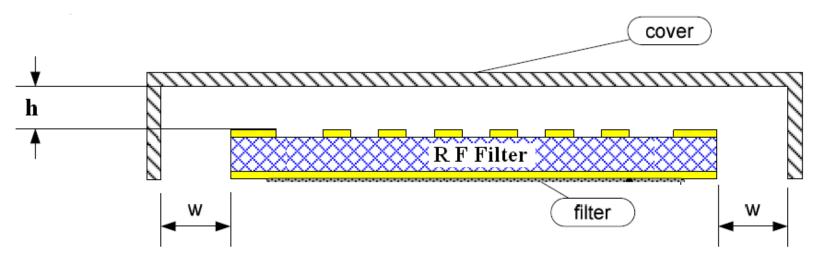
## Thin Film Filter – Notes



## **Filter Shielding:**

If the customer provides its own shielding for the filter, it is very important to know the channel width and cover height that will enclose the device. This dimension will be taken into account during the design and test to ensure the part will work in its next level of assembly.

Typically the distance from w from the part edge to the housing wall is recommended to be 0.25 to 0.40mm. Cover heights h are typically set to 3 to 5 times the thickness of the filter substrate. Standard filter thicknesses are 0.508 and 0.381mm.



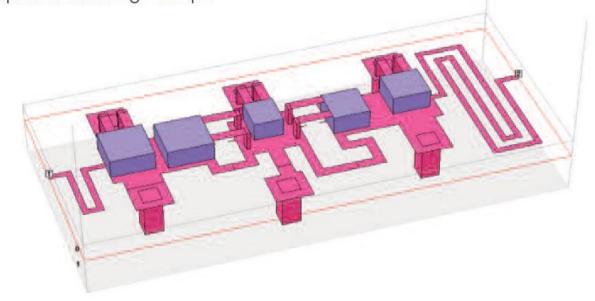






## **Thin Film Lumped Elements (TFLE)**

Small size and substrate-based material are perfect for SMT configurations such as Microstrip, Coplanar with Filled Vias, and Coplanar with Edge Wraps.



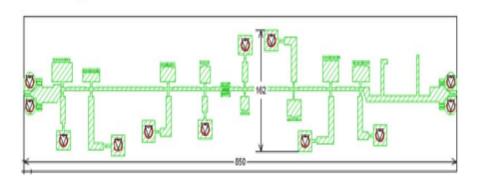
Example of TFLE Alumina Substrate Construction Measuring 0.25" x 0.16" x 0.1" with Cover

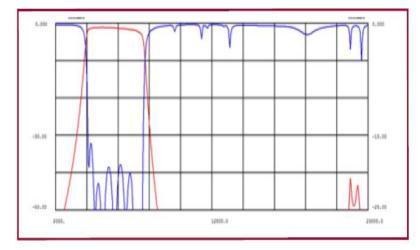






◆ Example: N=8+LPF, Fo=6000 MHz, BW=3500 MHz

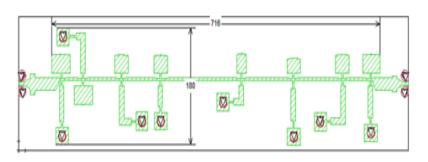


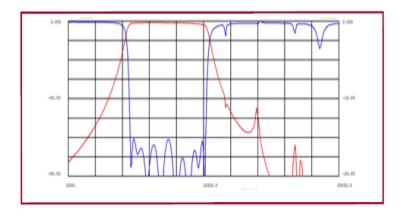


#### **TFLE:**

**BroadBand** 

◆ Example: N=8, Fo=10000 MHz, BW=5300 MHz





**Spurious Free** 

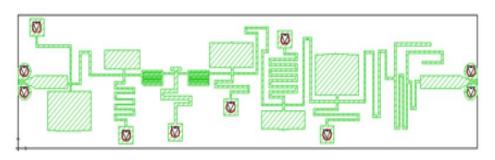
Versatile skewing factor

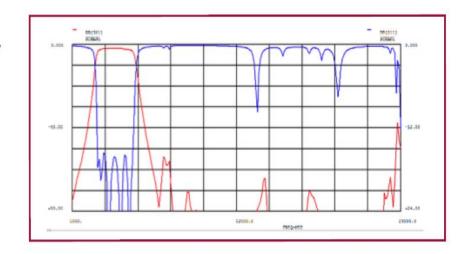




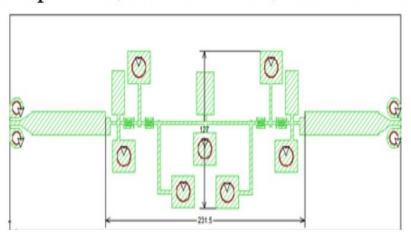
TECHNOLOGY DAYS
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18 APRIL

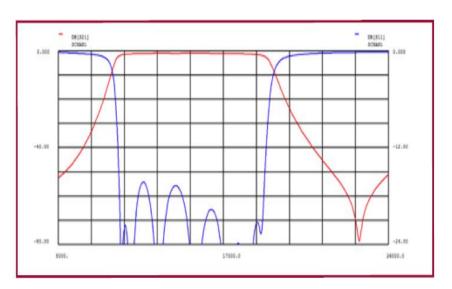
◆ Example: N=6+LPF, Fo=3800 MHz, BW=2200 MHz (57.8%), Measures: .85" x .2" x .02"





◆ Example: N=7, Fo=15000 MHz, BW=6600 MHz





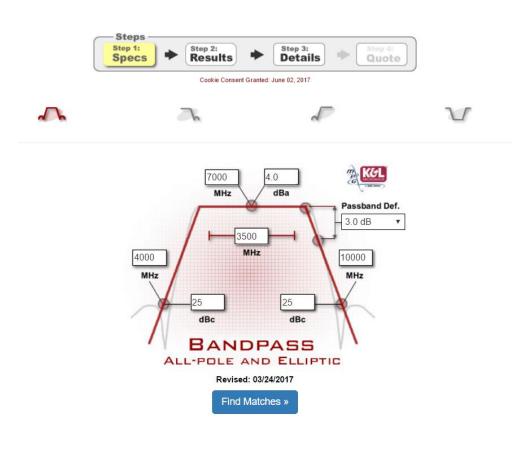




ınd



## Design tools





#### Filter Wizard® Search Results

Туре	<u>Item ID</u>	<u>L</u>	inch/mm	<u>I/O Type</u>	<b>G</b> o To
Film	8AB1-7000/E4145.2-1  Click to Hide	1.47 dBa	0.55 x 0.30 x 0.14 13.97 x 7.62 x 3.56	Launch ‡	Details »
Film	5TFA11-7000/T3500-1  Click to Hide	1.33 dBa	0.49 x 0.32 x 0.14 12.34 x 8.05 x 3.56	Launch ‡	Details »

# See Details screen for connector types other than default.

& See Details screen for interface options.

‡ See Details screen for launch type and cover options.

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Show All





Inches



#### Filter Wizard® Part: 5TFA11-7000/T3500-1

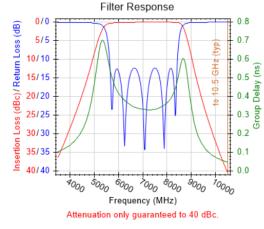
This part is a product of Dover Corporation's Microwave Products Group. Click here for information on all K&L Microwave® brand product offerings.

# K&L's Thin Film Lumped Element (TFLE) on Alumina parts require a cover for proper performance. Two Surface Mount Technology (SMT) bonding methods (solder and epoxy) and four end launch options are offered here. Hover the cursor on a launch option image for more information. Please contact the factory for further customization. Edge Wrap Castellated Open Ribbon Bond K&L Cover (required cover included)

Edge Wrap

Cover, SMT Bonding Method, and Launch Options

		Spec:	Typical:		
Center Frequency:		7000 MHz	7084.4 MHz		
3.0 dB Bandwidth:		3500 MHz	3500.0 MHz		
Insertion Loss:		1.5 dBa	1.33 dBa		
Stopband Atten. (4000 MHz):		25 dBc	28.50 dBc		
Stopband Atten. (10000 MHz):		28 dBc	32.10 dBc		
Filter Type:		Thin Film			
Spec Return Loss:		9.5 dB (2.0:1 VSWR)			
Typ Ult Rej:		10500 MHz			
Inches:	0.49 x 0.32 x 0.14 inches				
Millimeters:		12.34 x 8.05 x 3.56 mm			





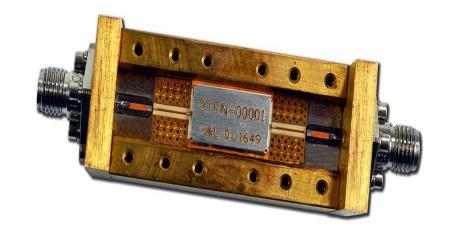






## **End Product Fully optimized for customer's PWB Transition**

- PWB information is exchanged
- Mismatch is analyzed on CST and optimized to match into  $50\Omega$ .
- Filter is designed in 50Ω system using Sonnet.
- The design is optimized accounting for the cascading of the S-parameter mismatch.
- Final Test fixture is made



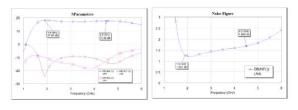




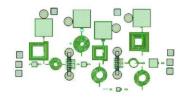


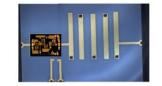
#### **Applications:**

- GPS Guided missile applications
- EW Airborne fighter jet requirements
- Satellite FM model filters where weight and volume are restricted.
- AESA Radar T/R Module or element array









Nominal 3dB passband : Passband Gain @ Fo RL (in/out)

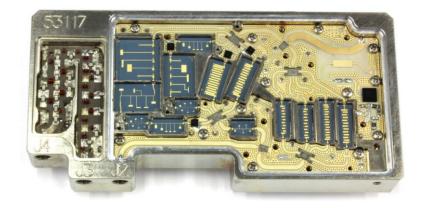
Iz 3

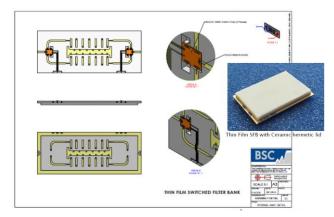
4GHz 46 26 +1

IP3 +24dBm Recovery TBD

Max Input power Surviva Max output power Size:

+25dBm (TB 15x10x1.5mm 10V @ 60mA













Questions?

Comments?

Find us at booth #17

